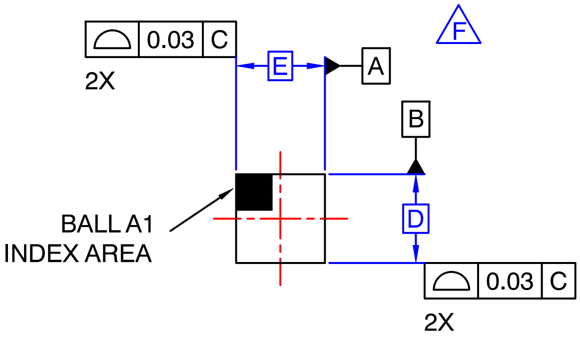
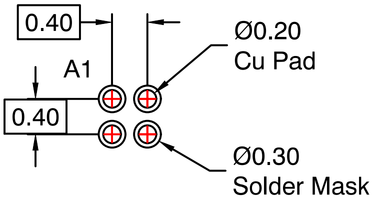
WLCSP4 0.8x0.8x0.5
CASE 567QP
ISSUE O

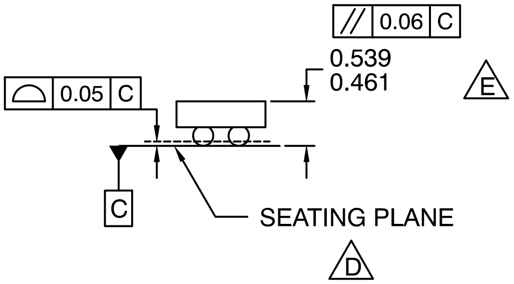
DATE 31 OCT 2016

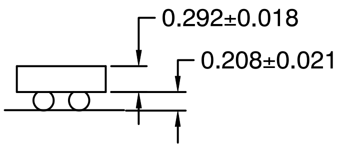


TOP VIEW

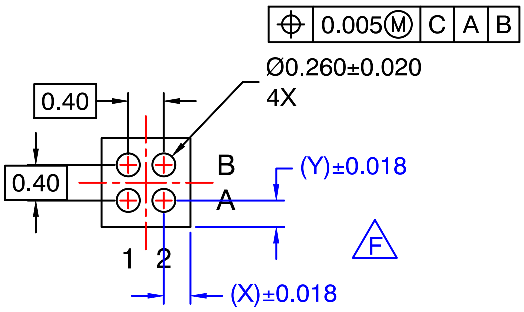


RECOMMENDED LAND PATTERN
(NSMD PAD TYPE)





SIDE VIEWS



BOTTOM VIEW

NOTES:

A. NO JEDEC REGISTRATION APPLIES.

B. DIMENSIONS ARE IN MILLIMETERS.

C. DIMENSIONS AND TOLERANCE PER ASME Y14.5M, 1994.

D. DATUM C IS DEFINED BY THE SPHERICAL CROWNS OF THE BALLS.

E. PACKAGE NOMINAL HEIGHT IS 500 MICRONS ±39 MICRONS (461−539 MICRONS).

F. FOR DIMENSIONS D, E, X, AND Y SEE PRODUCT DATASHEET.

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DESCRIPTION:	**WLCSP4 0.8x0.8x0.5**	**PAGE 1 OF 1**

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